



Material Content Data Sheet



Sales Product Name		BFQ 19S H6327		Issued		19. January 2018		
MA#		MA001208954						
Package		PG-SOT89-4-3		Weight*		53.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.017	0.03		317	
	noble metal	gold	7440-57-5	0.002	0.00		43	
	non noble metal	tin	7440-31-5	0.001	0.00	0.03	11	371
leadframe	inorganic material	silicon	7440-21-3	0.005	0.01		95	
	non noble metal	titanium	7440-32-6	0.025	0.05		475	
	non noble metal	chromium	7440-47-3	0.076	0.14		1425	
	non noble metal	copper	7440-50-8	25.112	47.30	47.50	472931	474926
wire	noble metal	gold	7440-57-5	0.018	0.03	0.03	340	340
encapsulation	organic material	carbon black	1333-86-4	0.270	0.51		5079	
	plastics	epoxy resin	-	4.045	7.62		76183	
	inorganic material	silicondioxide	60676-86-0	22.653	42.66	50.79	426626	507888
leadfinish	non noble metal	tin	7440-31-5	0.801	1.51	1.51	15091	15091
plating	noble metal	silver	7440-22-4	0.073	0.14	0.14	1384	1384
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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